

## DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	6.0	+0.0/-0.0	PLATED	129
e	8.0	+0.0/-8.0	PLATED	15
.	8.0	+3.0/-12.0	PLATED	2085
.	12.2	+3.0/-3.0	PLATED	64
e	24.0	+0.0/-0.0	PLATED	50
F	33.46	+0.0/-0.0	PLATED	1
H	37.4	+0.0/-0.0	PLATED	9
I	38.0	+0.0/-0.0	PLATED	50
J	38.0	+0.0/-0.0	PLATED	36
K	41.34	+0.0/-0.0	PLATED	10
L	44.0	+0.0/-0.0	PLATED	40
M	50.0	+0.0/-0.0	PLATED	16
N	82.68	+3.0/-3.0	PLATED	8
O	120.0	+2.0/-2.0	PLATED	2
P	140.0	+0.0/-0.0	PLATED	1
Q	250.0	+0.0/-0.0	PLATED	2
R	47.01	+0.0/-0.0	NON-PLATED	4
s	50.0	+0.0/-0.0	NON-PLATED	4
T	61.02	+0.0/-0.0	NON-PLATED	2
U	130.0	+0.0/-0.0	NON-PLATED	12

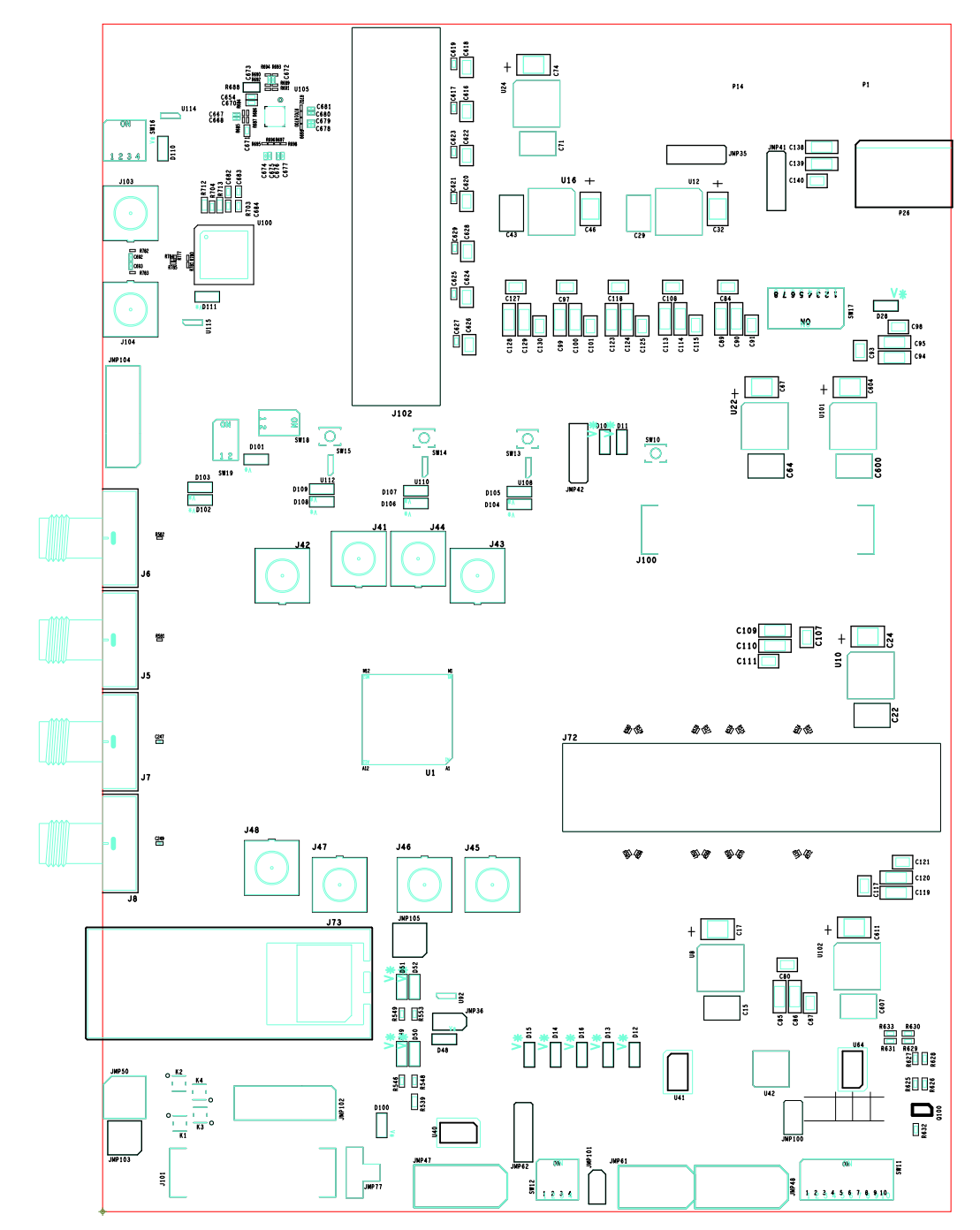


7 6 5 4 3 2 1

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	TLK10xxx EVM MOTHER BOARD	04/16/13	J. NERGER

D  
C  
B  
A

D  
C  
B  
A



STW

7 6 5 4 3 2 1

UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE	Texas Instruments Inc. 12500 TI Boulevard Dallas, TX 75243		
DIMENSIONS ARE IN INCHES		DRAWN	LT/DFW TEST	04/16/13	<b>ASSEMBLY</b> <b>TLK10xxx EVM MOTHER BOARD</b>		
TOLERANCES ON:		CHECKED	J. NERGER	04/16/13			
2 PL DECIMALS -		ENGRG	J. NERGER	04/16/13			
3 PL DECIMALS -		ISSUED	J. NERGER	04/16/13			
ANGLES -					SIZE	FSCM NO	DWG NO
FRACTIONS -					6566789		
					SCALE	SHEET 1 / 2	

7

6

5

4

3

2

1

D

D

C

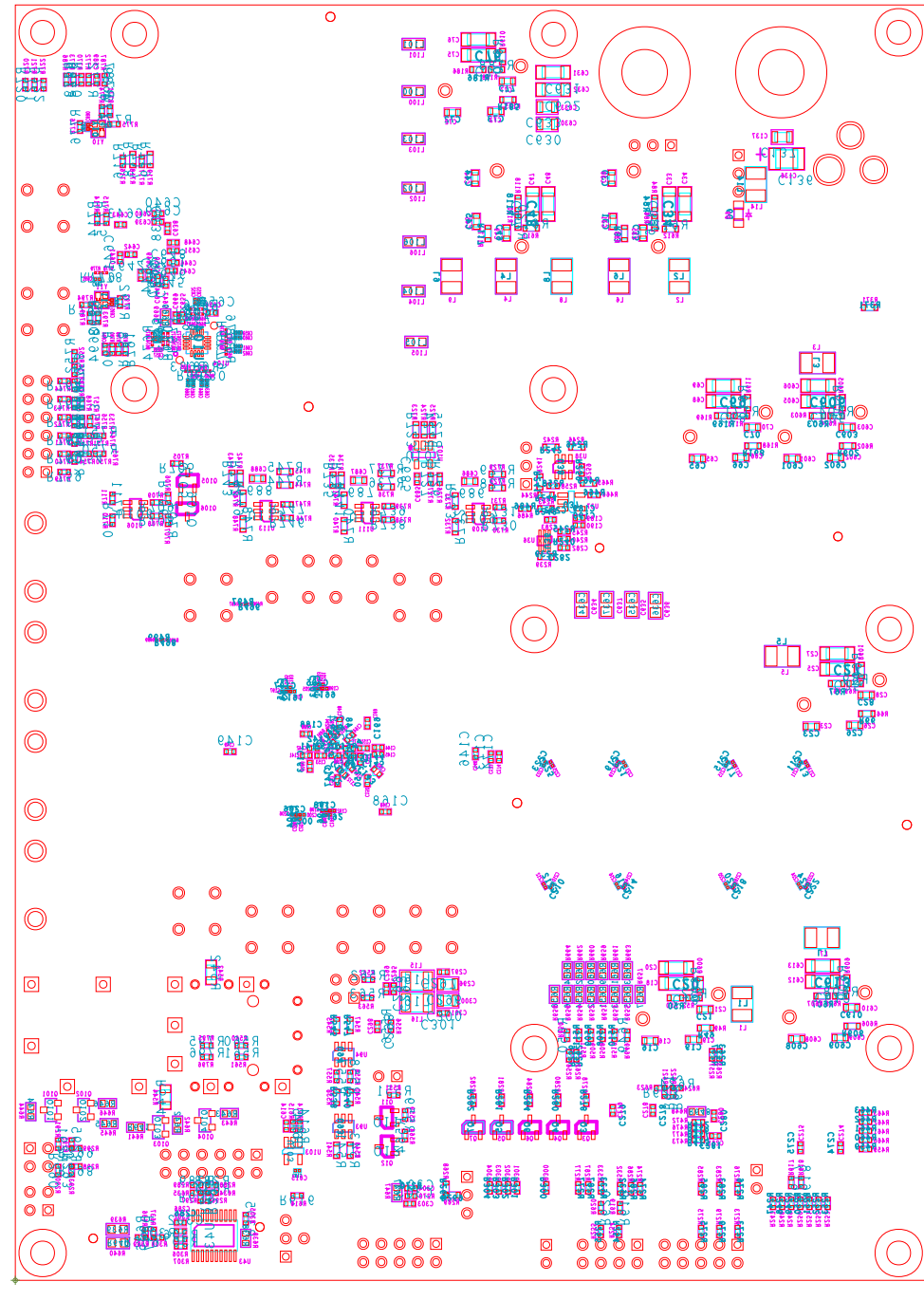
C

B

B

A

A



REVISIONS			
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ANGLES -					SIZE	FSCM NO	DWG NO
FRACTIONS -							6566789
					SCALE	SHEET 2 / 2	

7

6

5

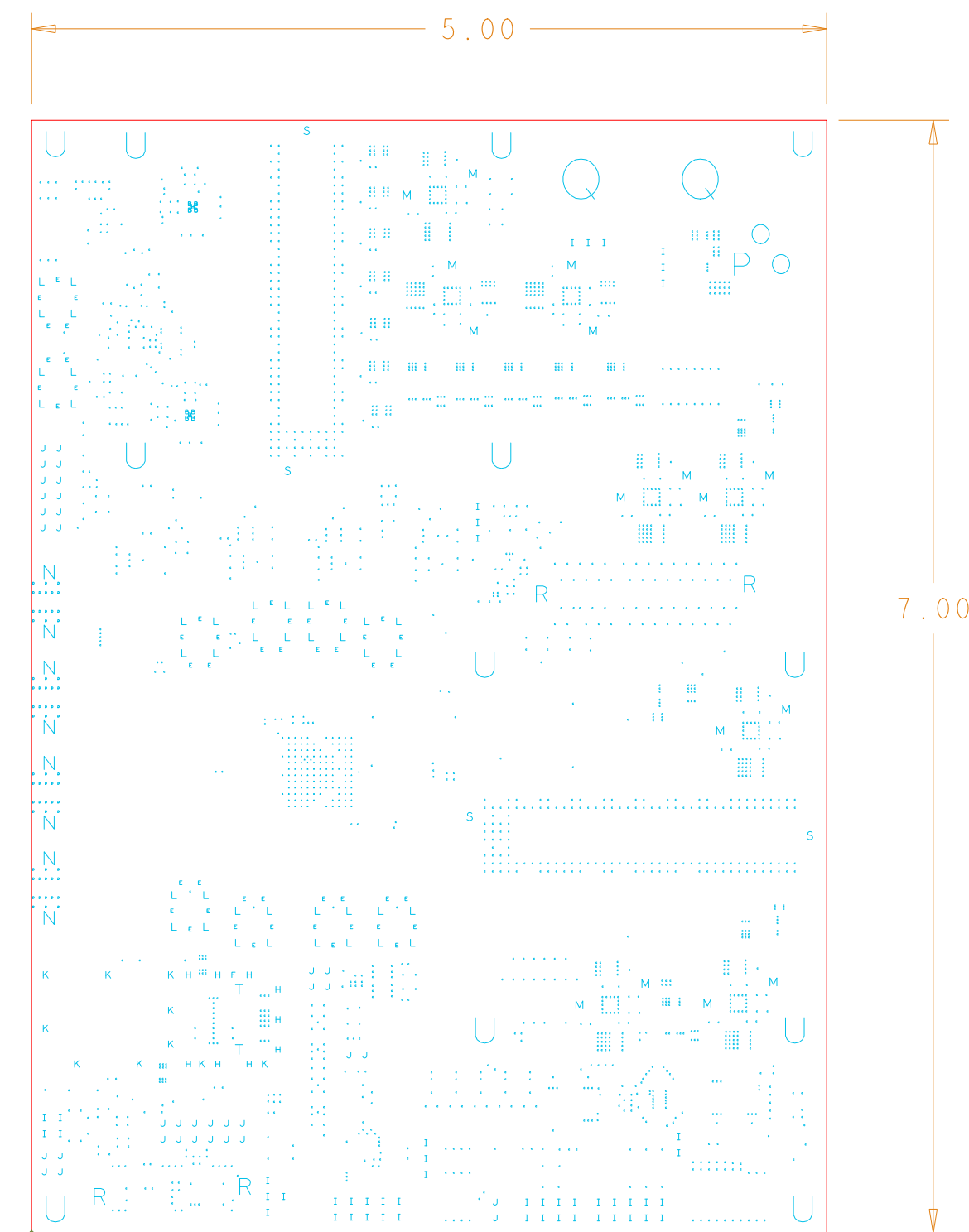
4

3

2

1

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	TLK10xxx EVM MOTHER BOARD	04/16/13	J. NERGER



DRILL CHART: TOP to BOTTOM				
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U	130.0	+0.0/-0.0	NON-PLATED	12

GENERAL NOTES. UNLESS OTHERWISE SPECIFIED

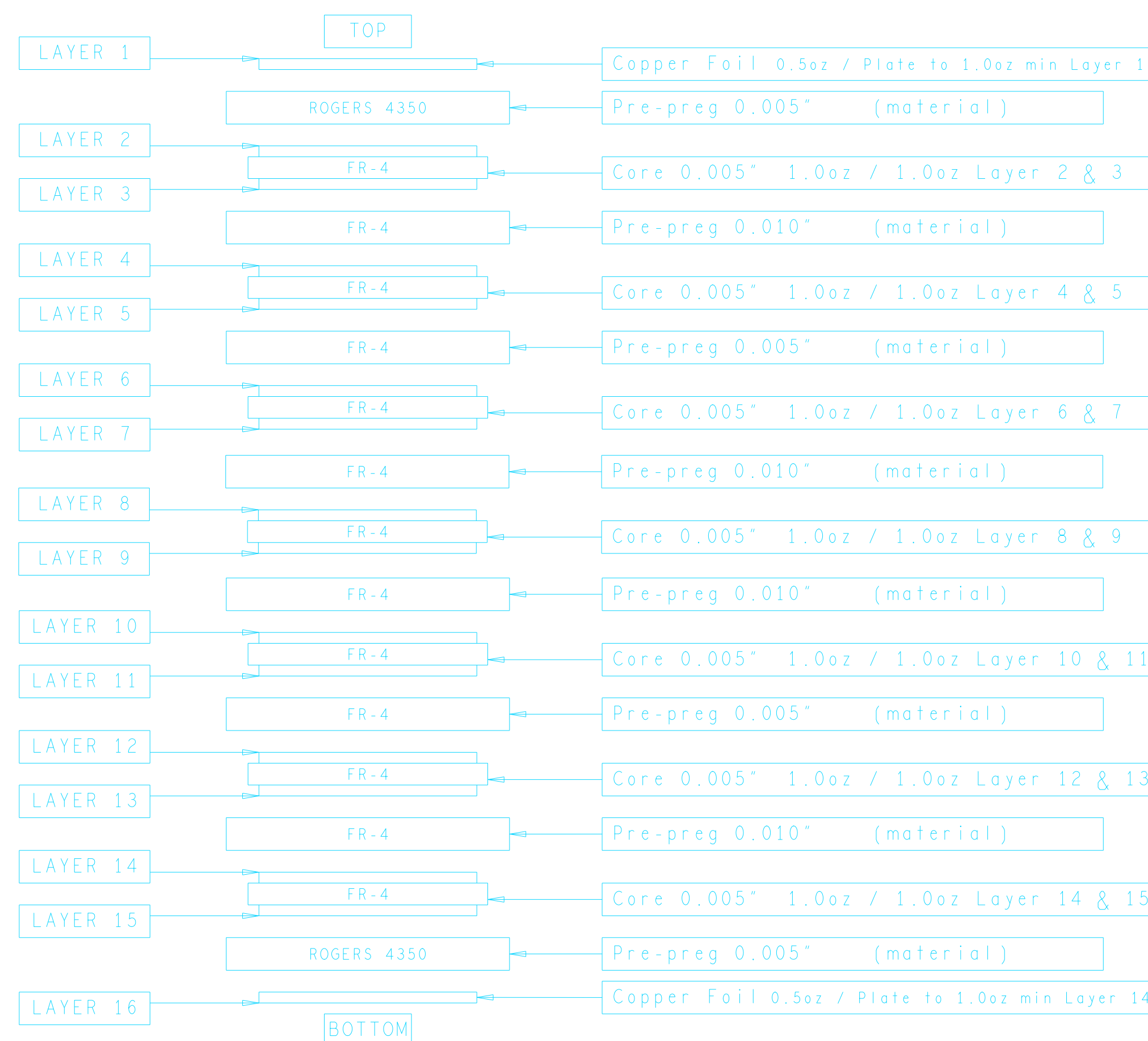
- ALL FABRICATION ITEMS MUST MEET OR EXCEED BEST INDUSTRY PRACTICE : IPC-A-600C (Commercial std)
- LAMINATE MATERIAL : ROGERS 4350B or EQUIVALENT BETWEEN LAYERS 1 & 2 AND LAYERS 15 & 16
- FR4 POLYCLAD OR EQUIVALENT FOR ALL OTHER LAYERS
- COPPER WEIGHT : 1oz START INTERNAL, 1/2oz START EXTERNAL
- FINISHED BOARD THICKNESS : .111 +/-10%
- MAXIMUM WARP AND TWIST TO BE : .005 INCH PER INCH
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE : .001 INCH. THERE MUST BE .1MIL OR GREATER PLATING ON EACH SIDE OF THE BARREL WHEN VIEWED IN THE CROSS SECTION
- MINIMUM ANNULAR RING OF PLATED-THRU HOLES TO BE : .002 INCH
- MINIMUM ALLOWABLE LINE REDUCTION TO BE 20% OR .002 WHICHEVER IS GREATER
- 0.010 SIGNAL LINES ON LAYERS 1 & 16 TO BE IMPEDANCE CONTROLLED 50 OHMS +/- 10%
- 0.008 SIGNAL LINES ON LAYER 3, 8, 14 TO BE IMPEDANCE CONTROLLED 50 OHMS +/- 10%
- 0.0045 SIGNAL LINES ON LAYER 1, 3, 8, 16 TO BE IMPEDANCE CONTROLLED 100 OHMS +/- 10%
- DIELECTRIC CONSTANTS ARE :  
ROGERS 4350: 3.6  
FR4 POLYCLAD: 4.1
- VIA'S IN SMT DEVICE PADS TO BE FILLED WITH NON-CONDUCTIVE EPOXY. ANY VOID IN THE FILL MATERIAL MUST NOT BE GREATER THAN 25% OF THE FINISHED HOLE DIAMETER. SEE DRILL NOTE #1
- A CROSS SECTION MOUNT AND DIGITAL PHOTO'S OF VIA'S TO BE PROVIDED
- USE THE (DRPP) DUTCH REVERSE PLATING PROCESS

PROCESS NOTES

- CIRCUITRY ON OUTER LAYERS TO BE PLATED WITH : NICKEL GOLD
- SOLDEMASK BOTH SIDES PER ARTWORK : BLUE LPI
- SILKSCREEN BOTH SIDES PER ARTWORK : COLOR : WHITE

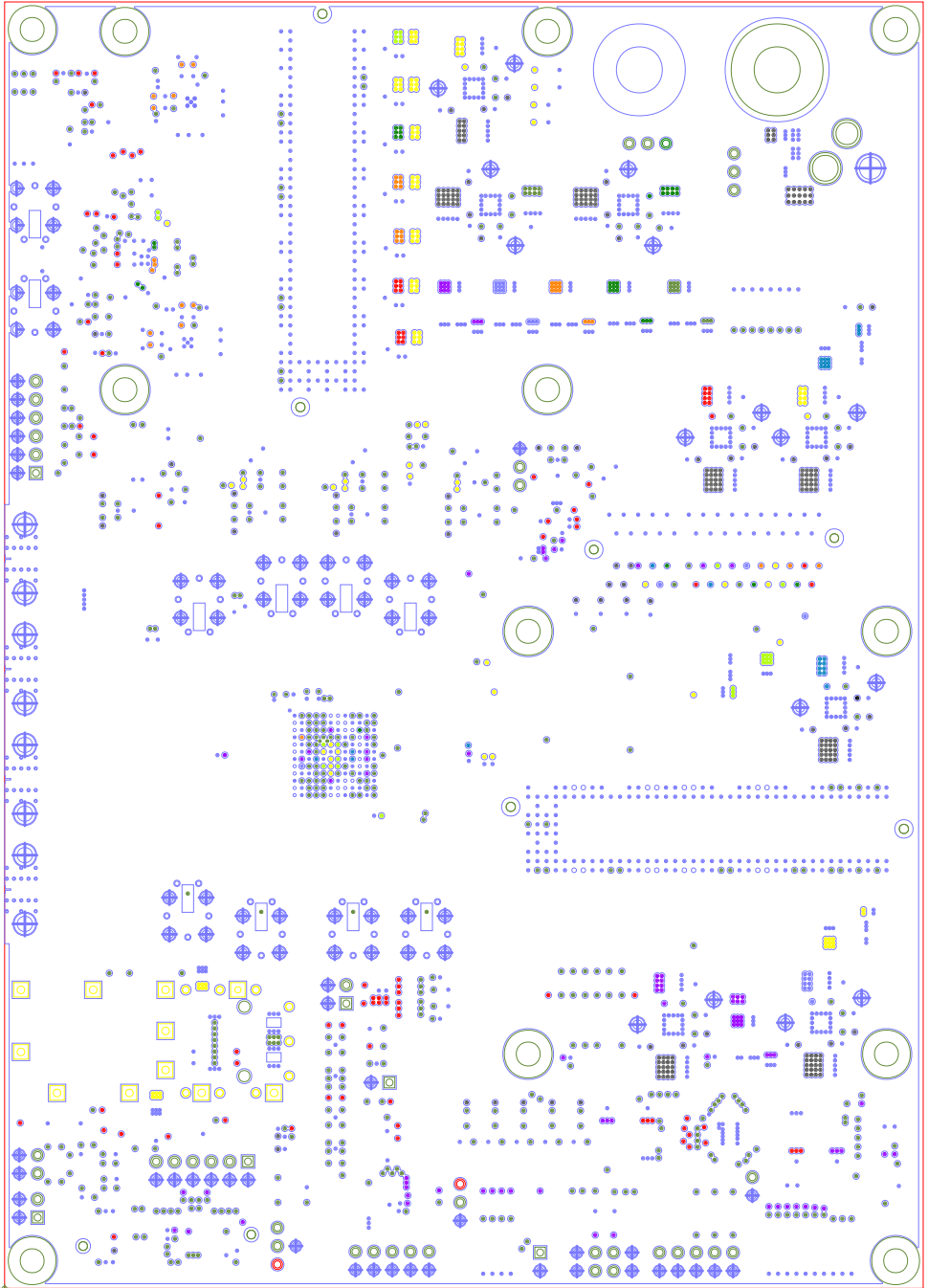
DRILL NOTES

- 0.0081" DRILL SHOULD NOT BE EXPOY FILLED.
- 0.0081" DRILL IS A REFERENCE NAME, ALL 0.0081" DRILLS SHOULD BE DRILLED TO 0.008".



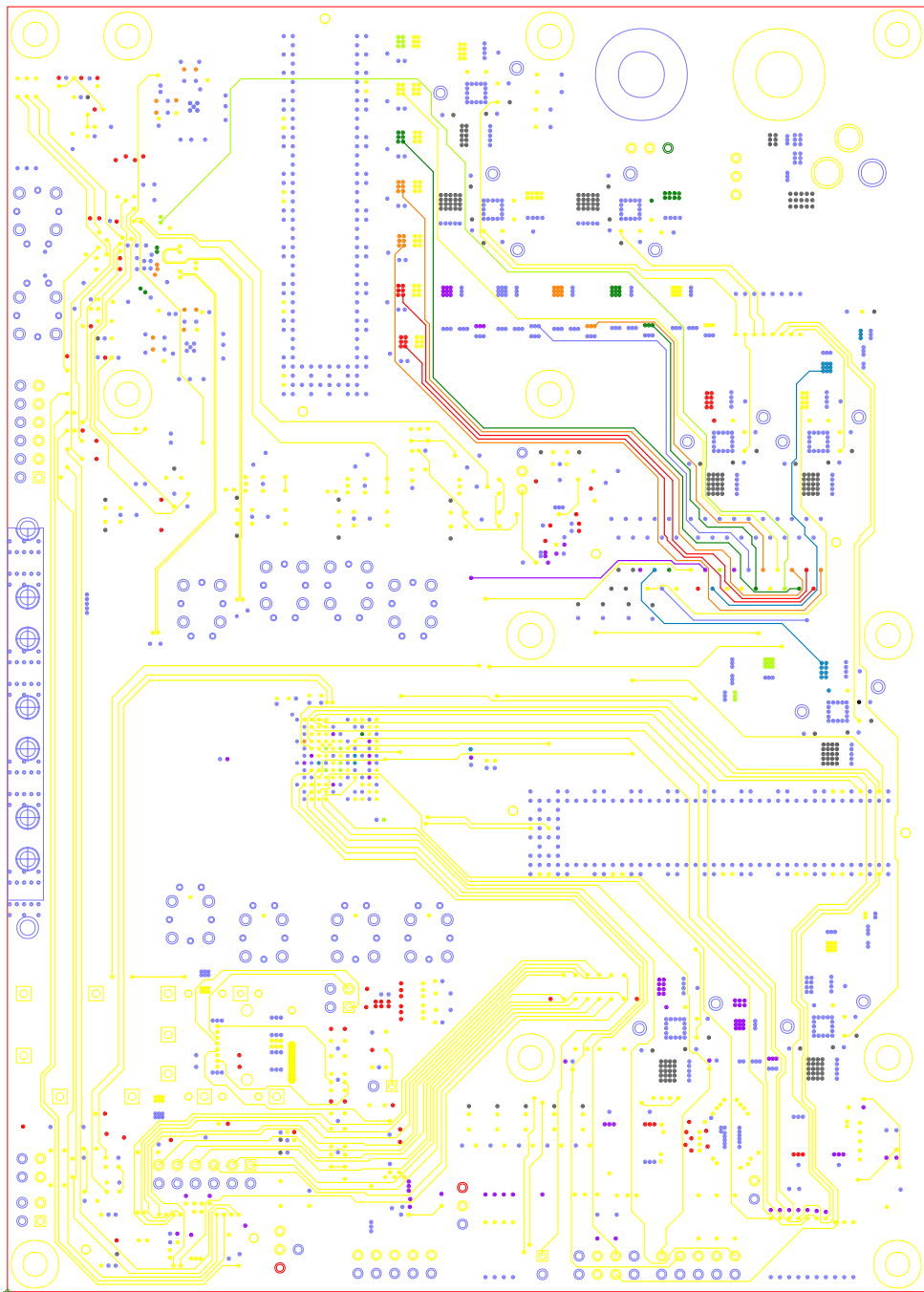
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3 PL DECIMALS -		ISSUED	J. NERGER	04/16/13	
ANGLES -					
FRACTIONS -					
		SIZE	FSCM NO	DWG NO	6566789
		SCALE			SHEET 1 / 1





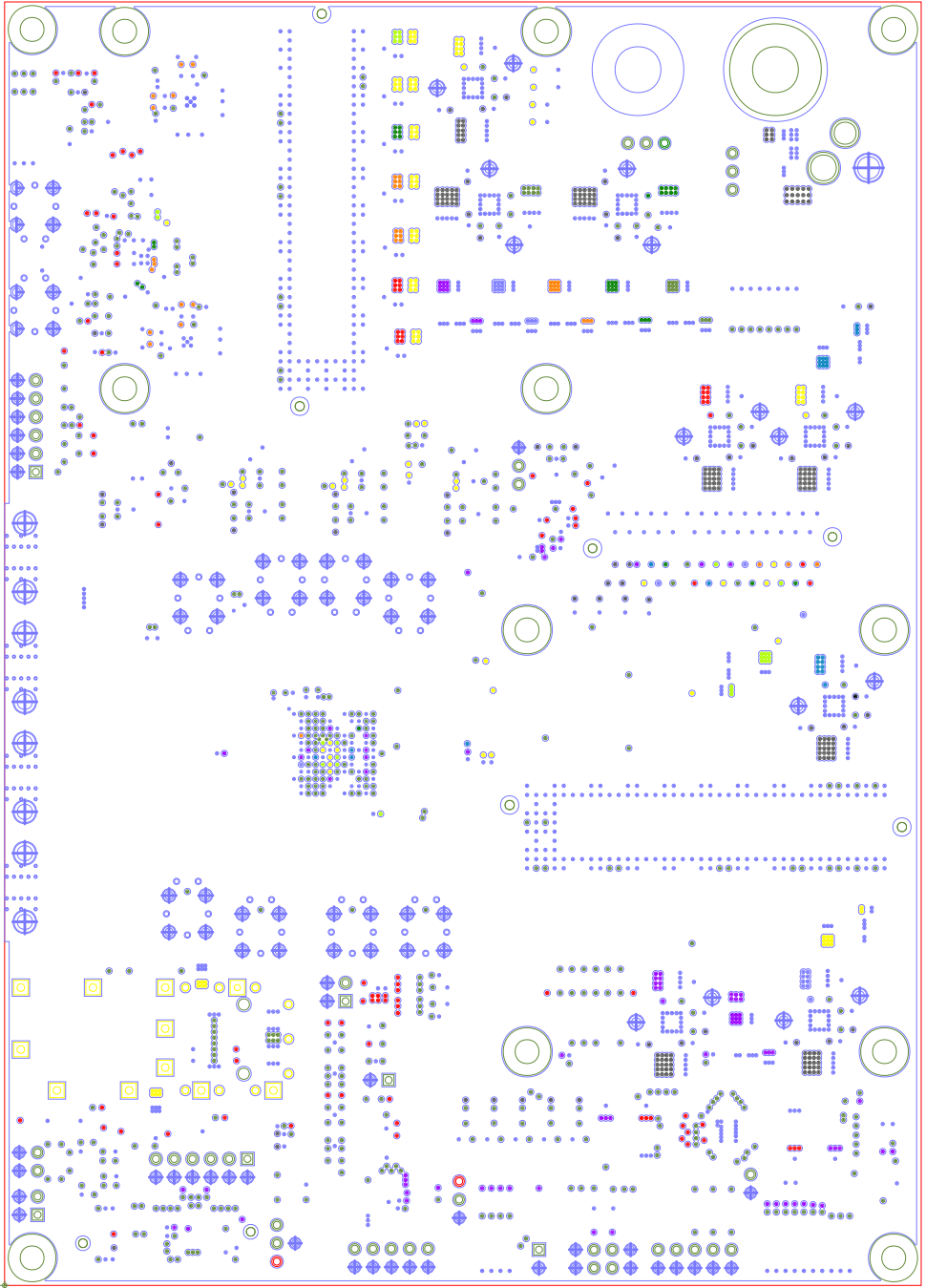
LAYER2 - GND



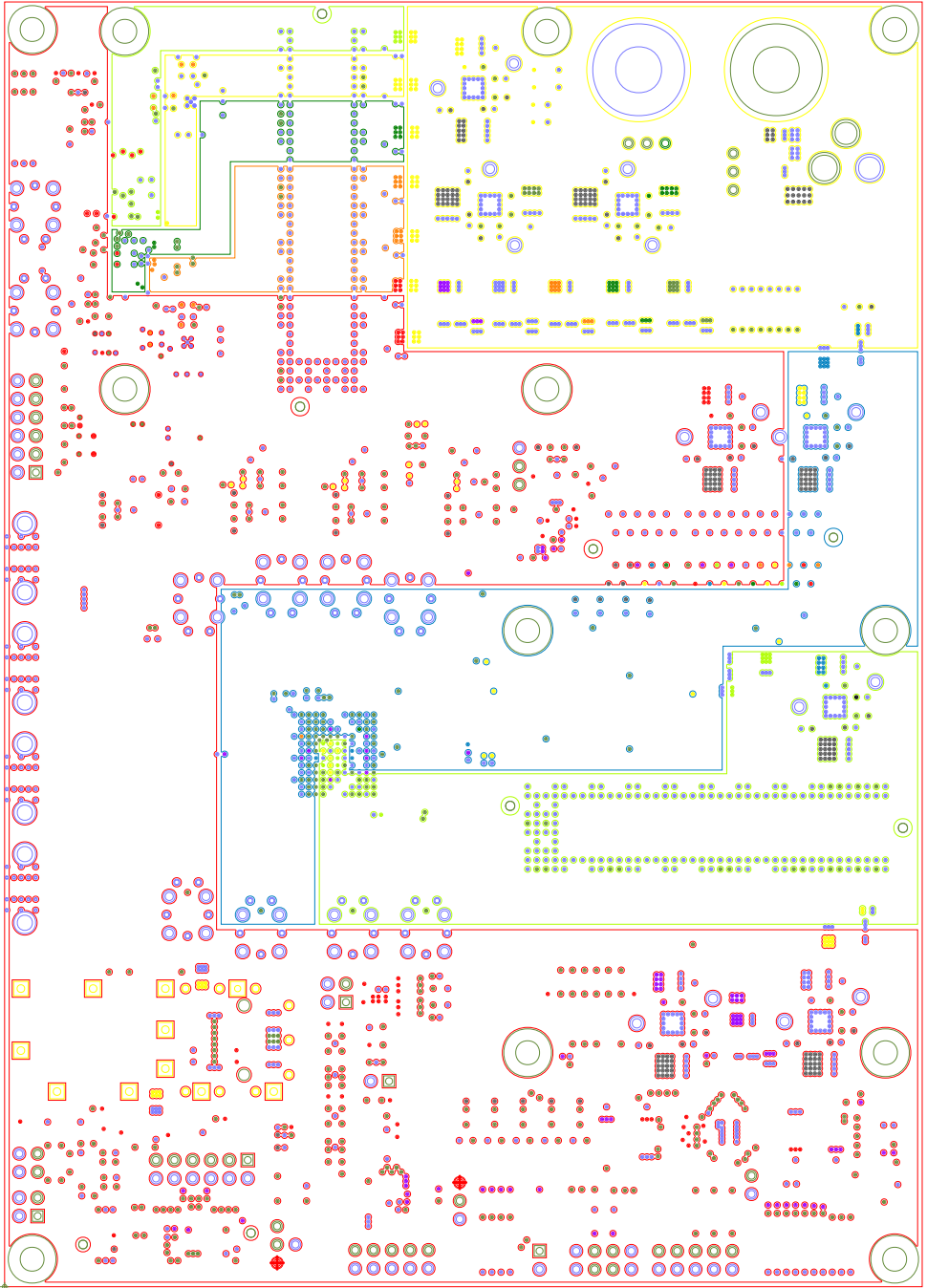


LAYER3 - SIGNAL

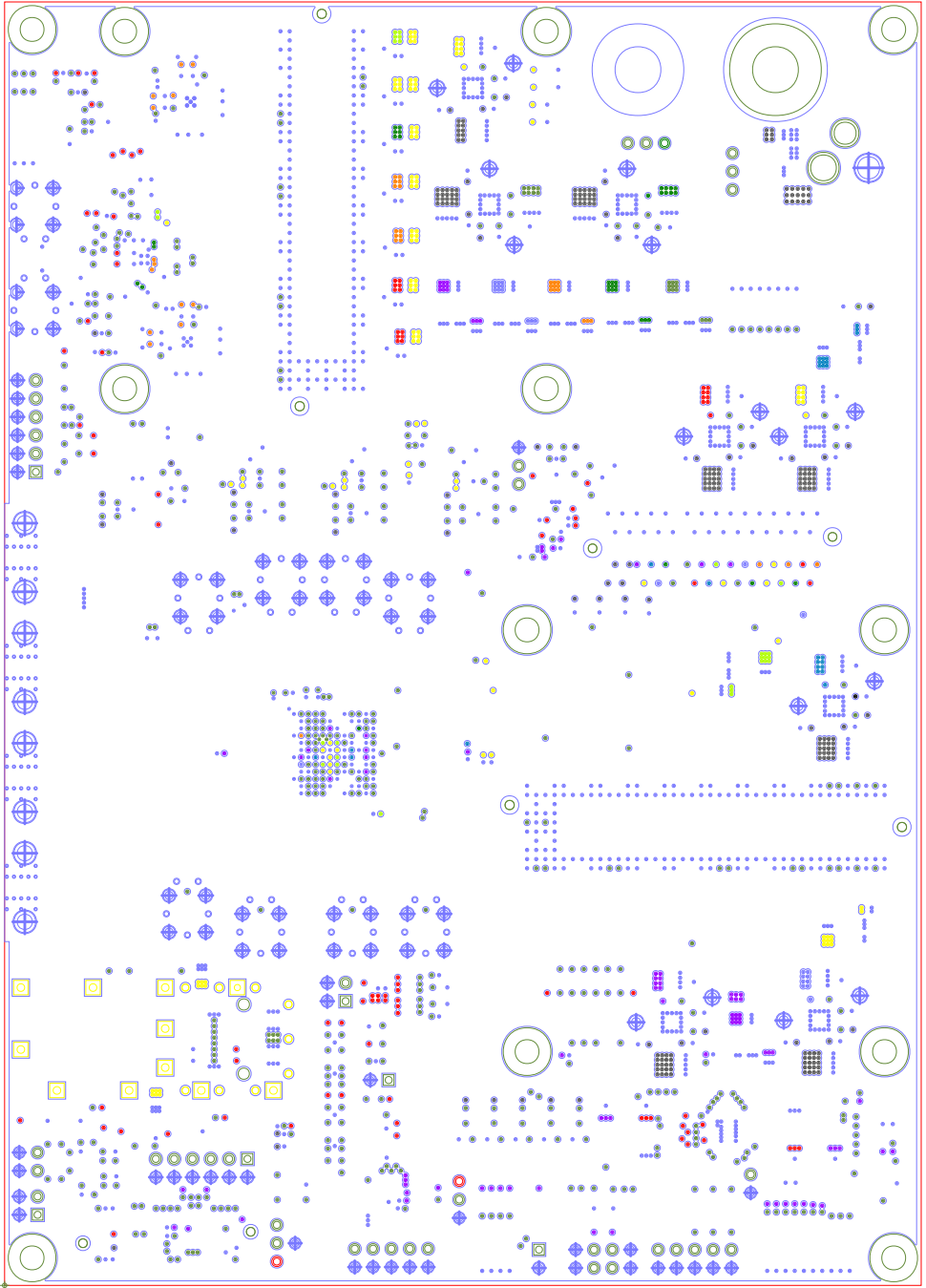




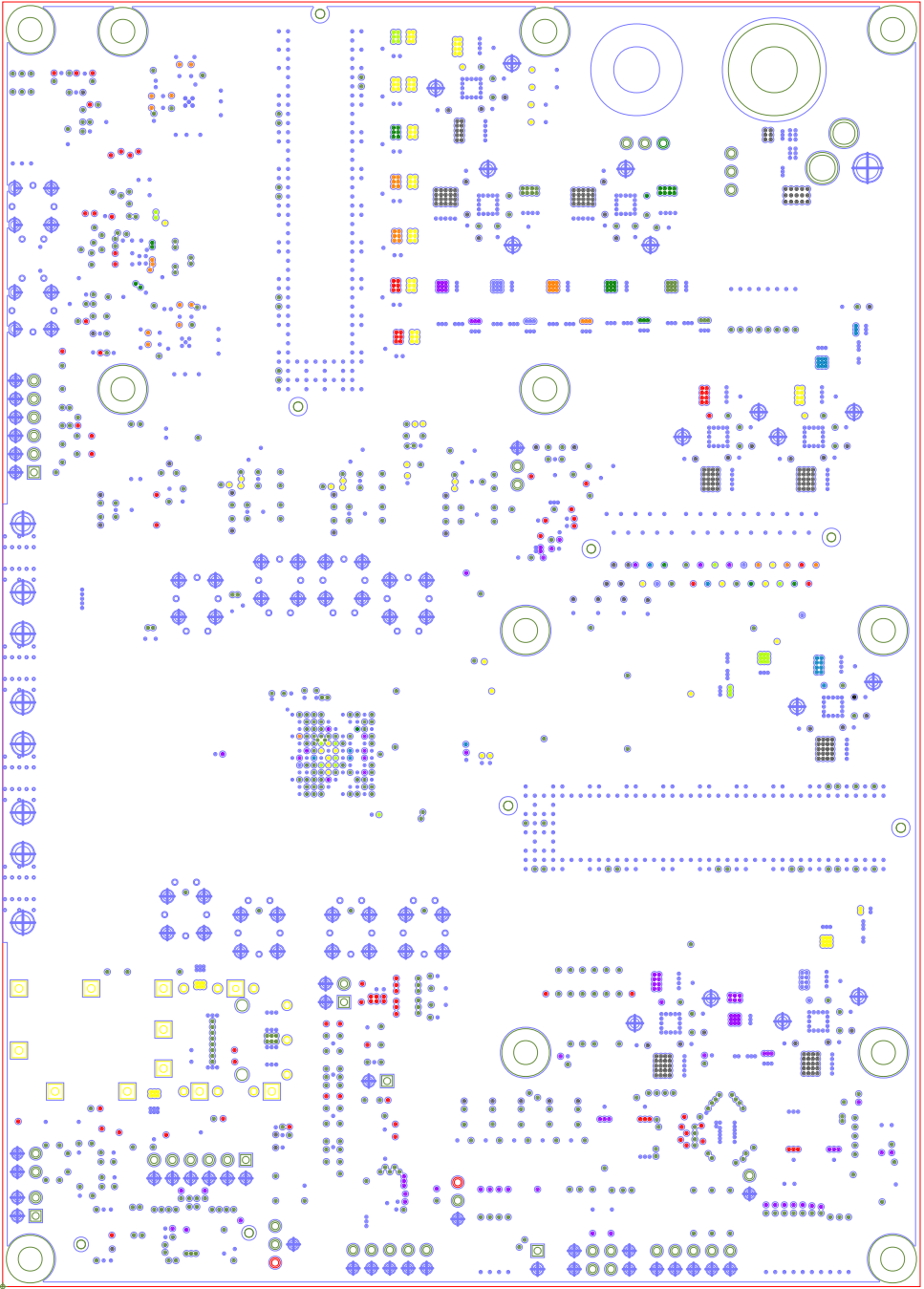
LAYER4 - GND



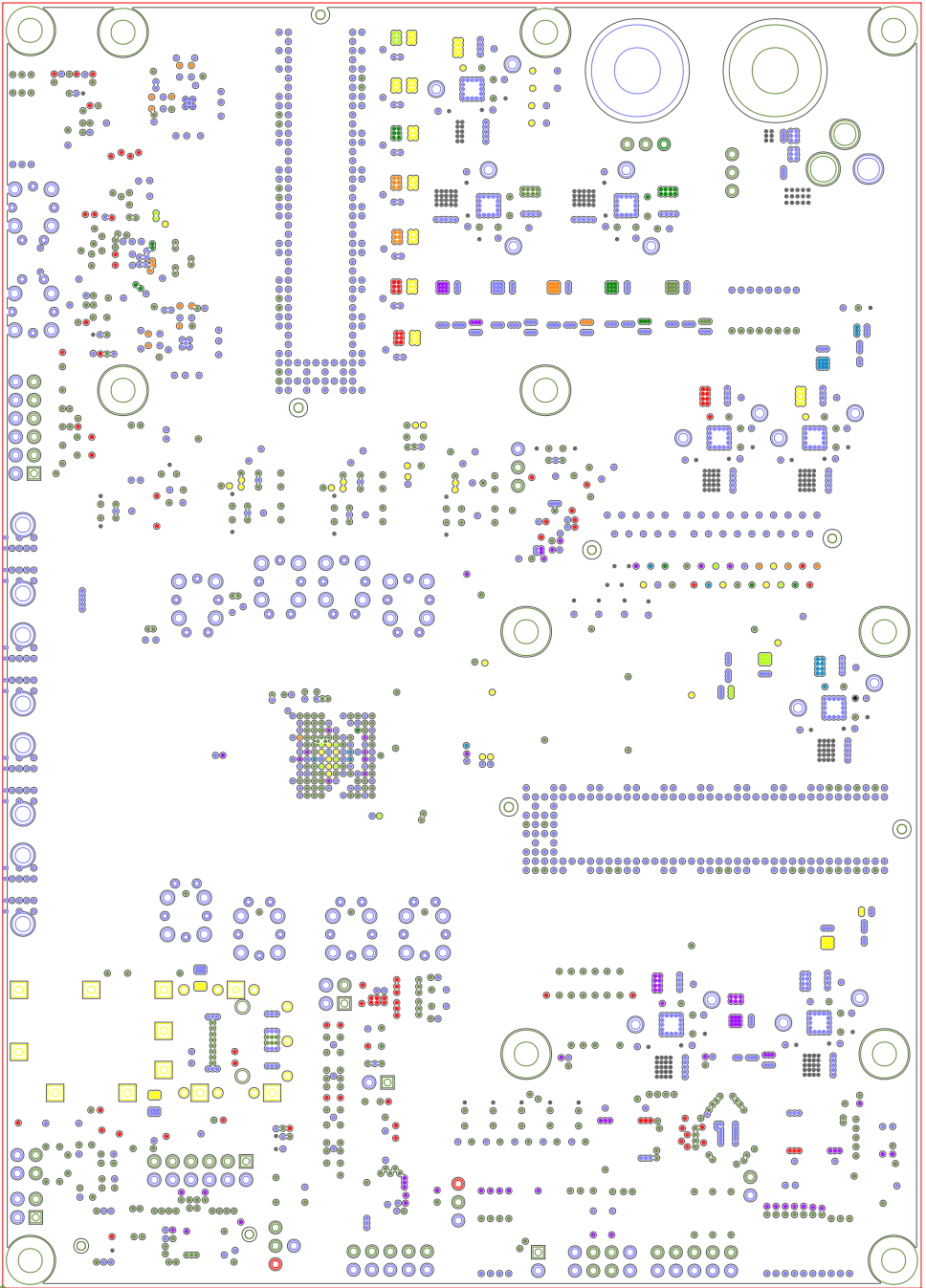
LAYER5 - PWR



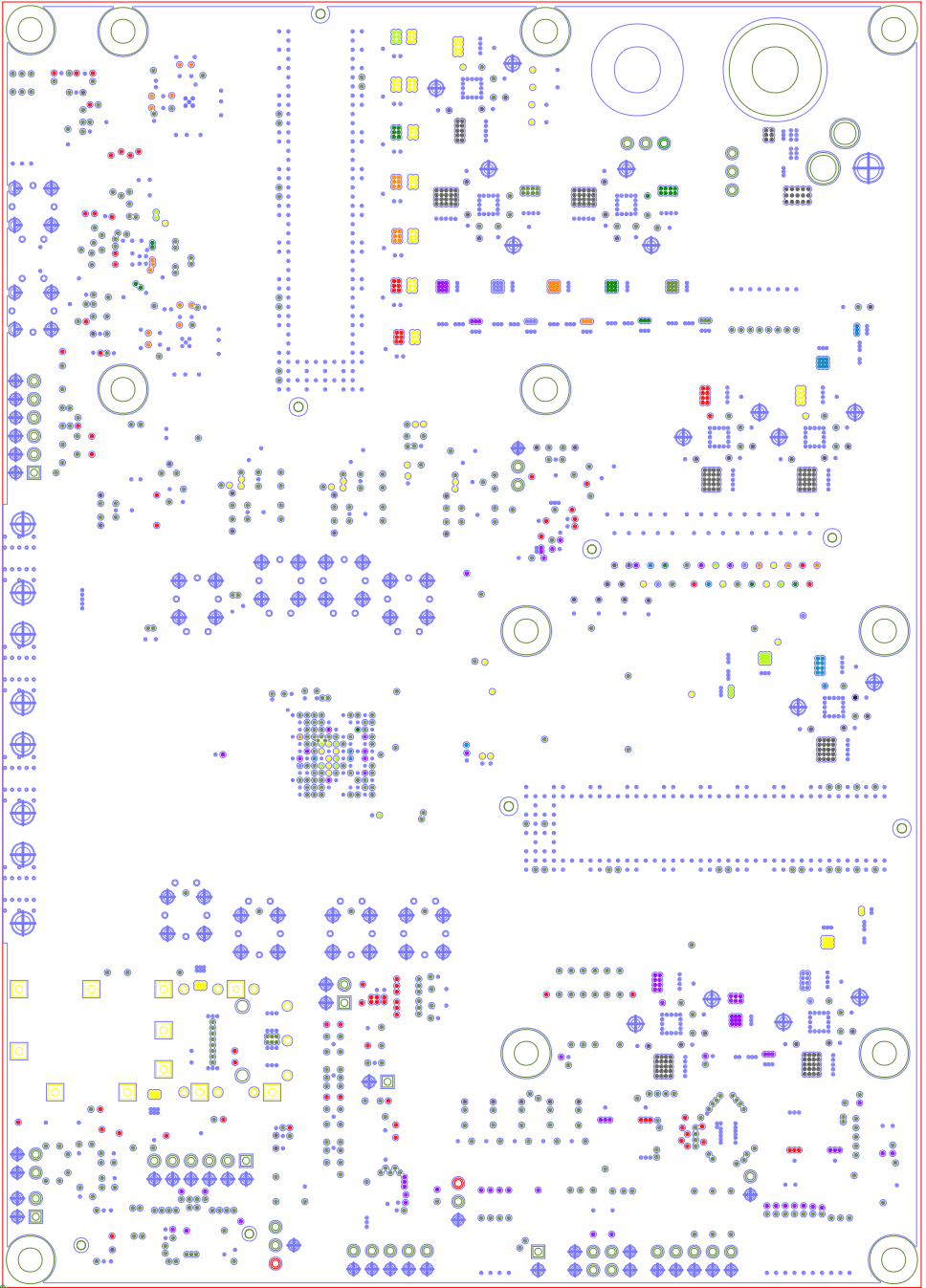
LAYER6 - GND



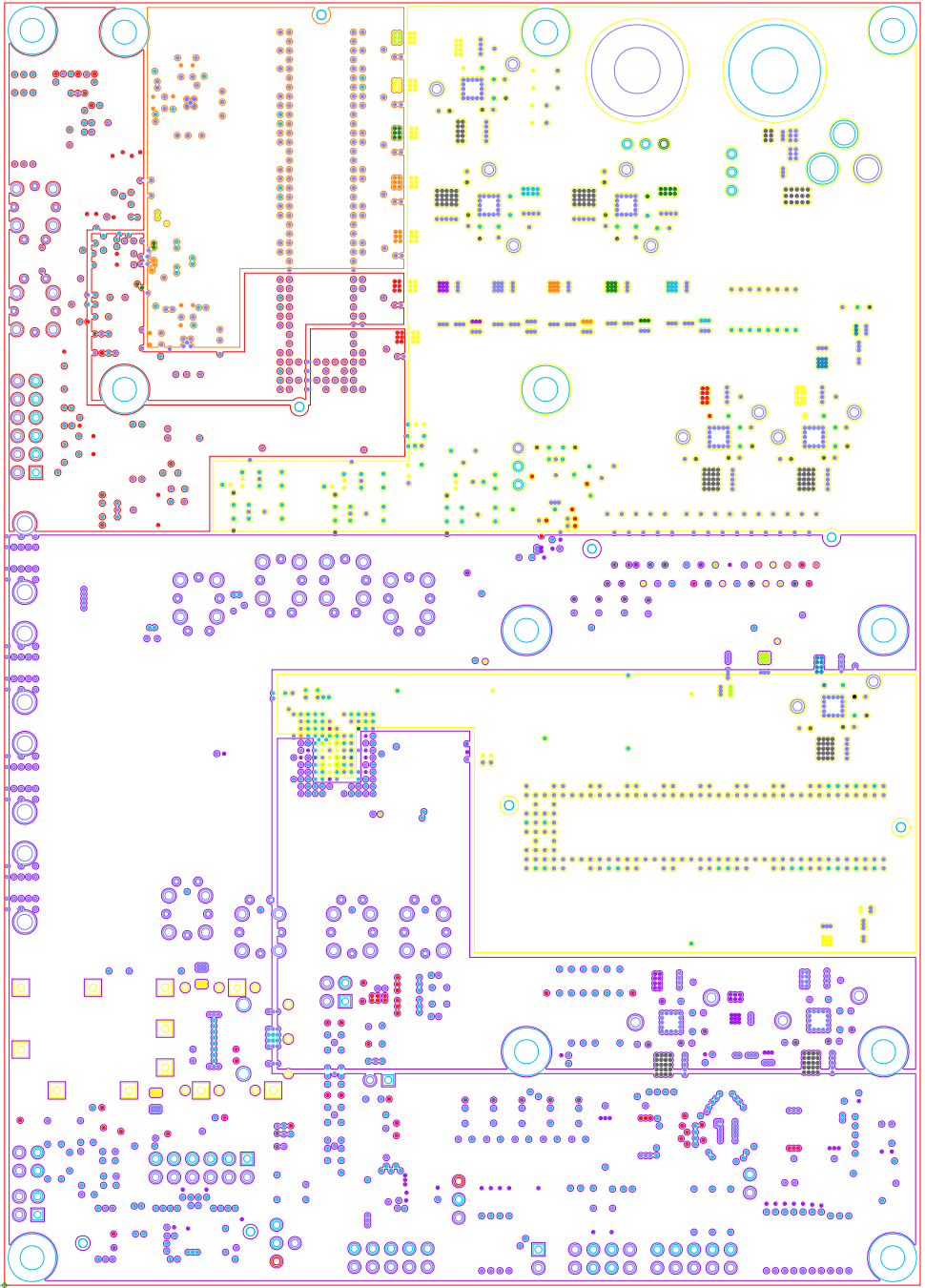
LAYER 9 - GND



LAYER10-PWR

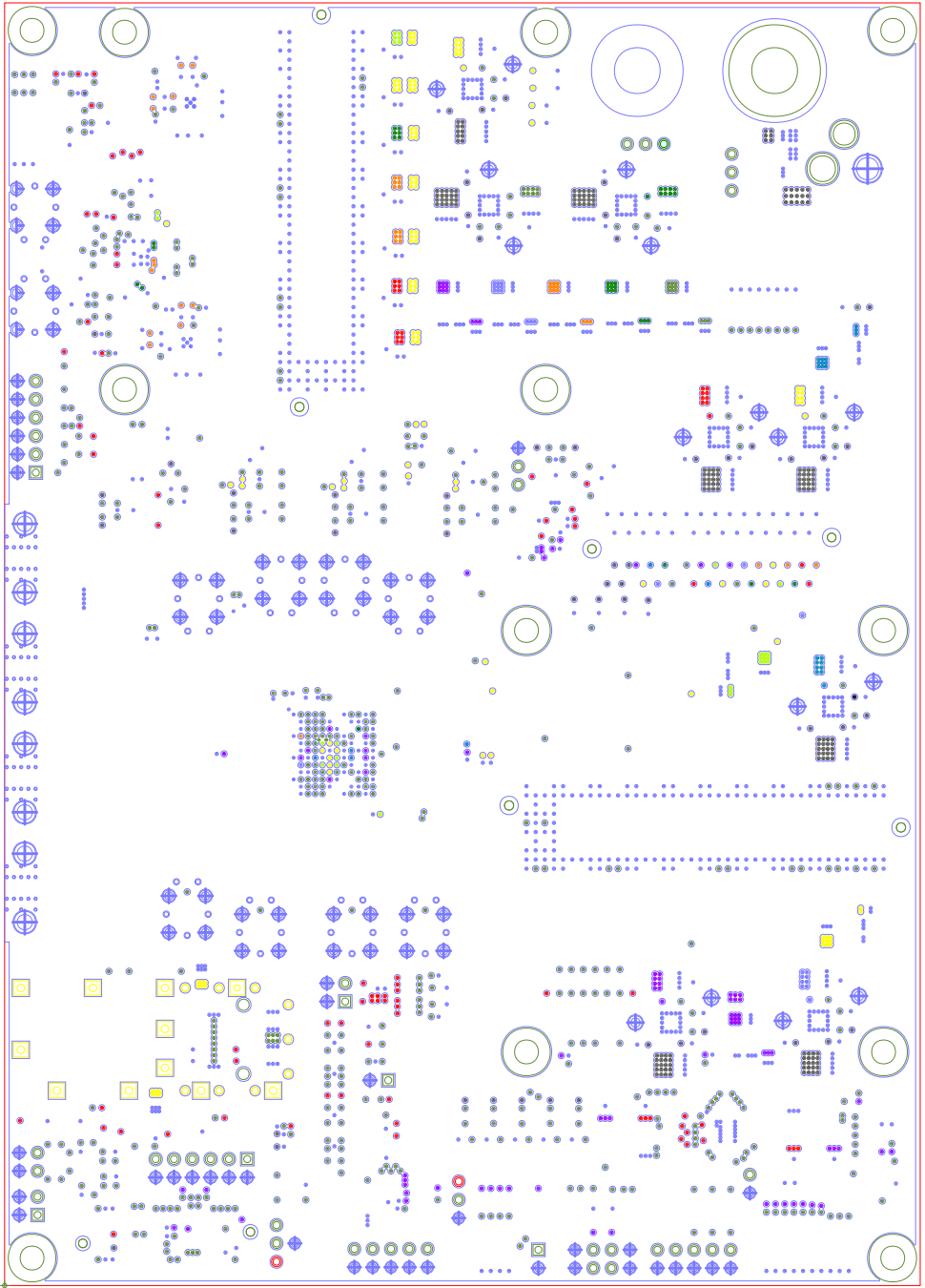


LAYER11 - GND

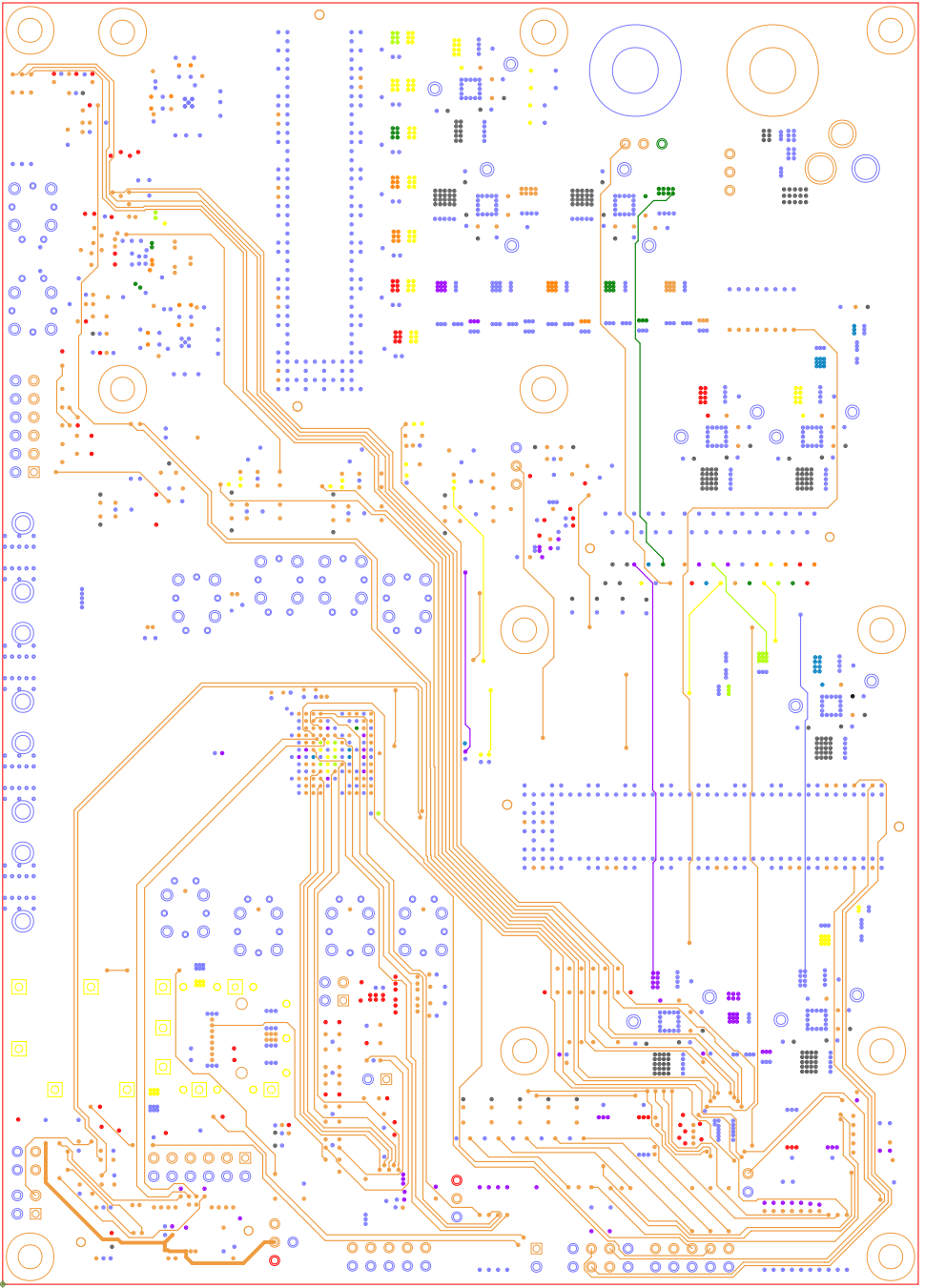


LAYER12 -PWR

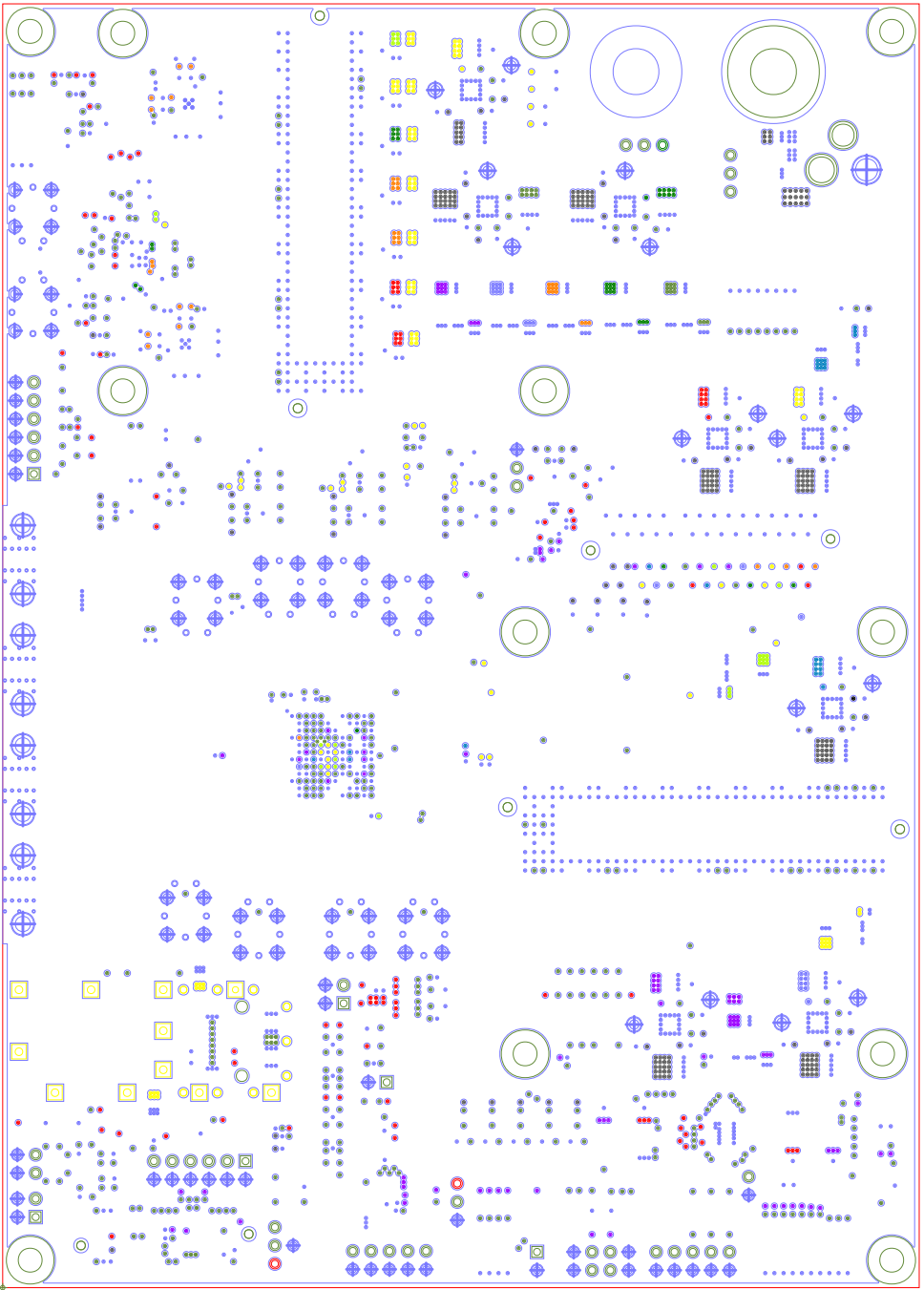




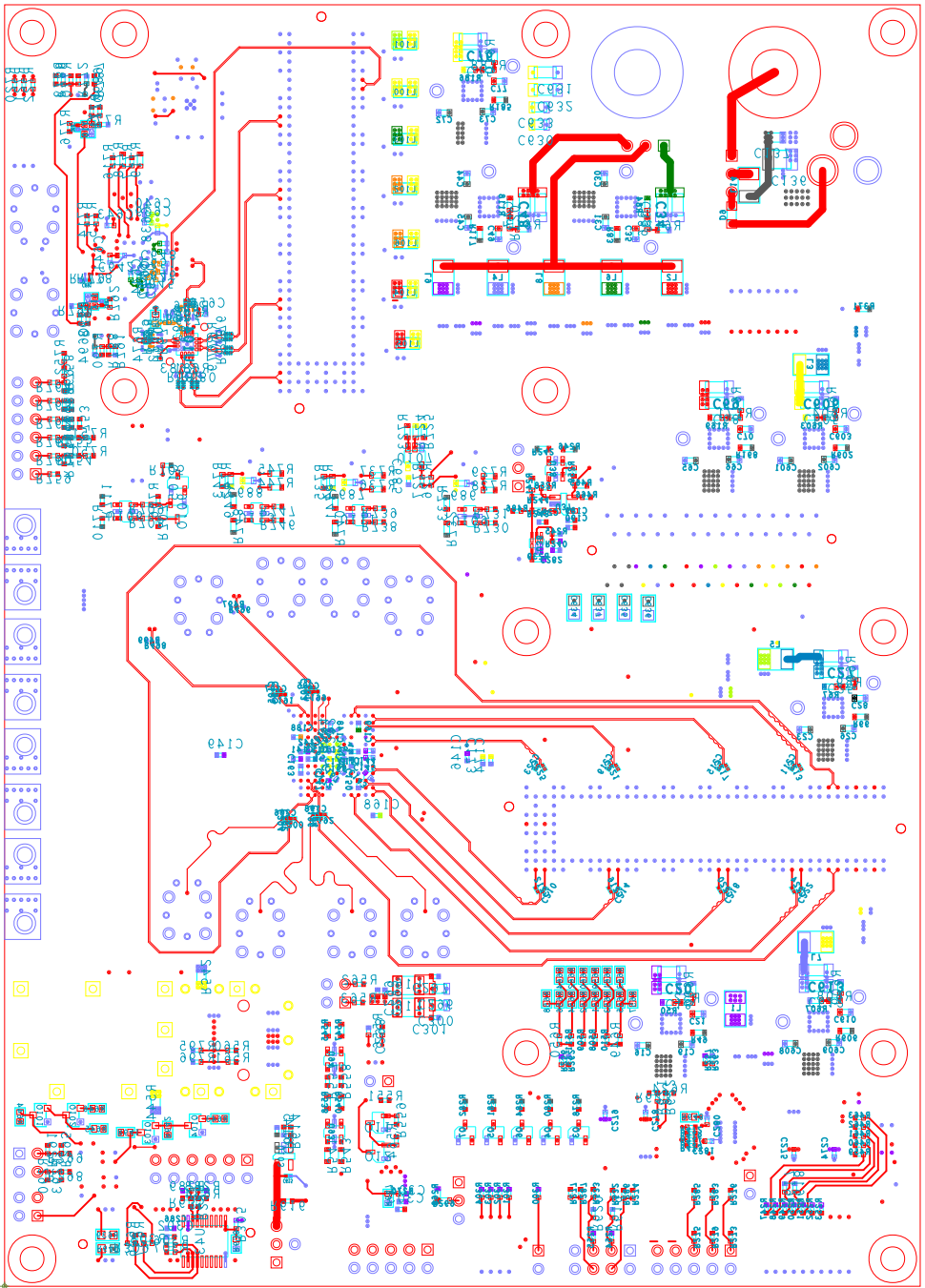
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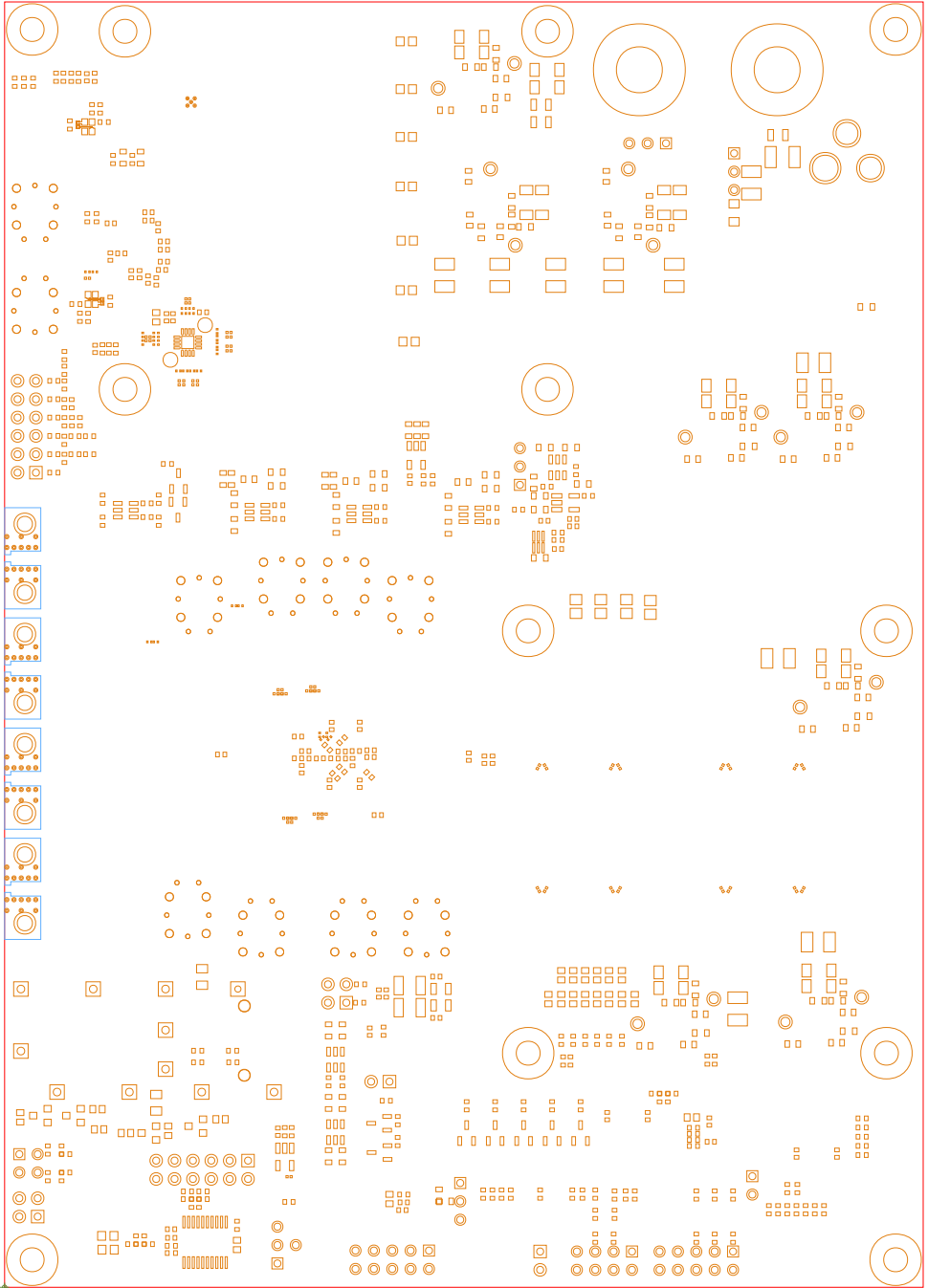
LAYER14-SIGNAL



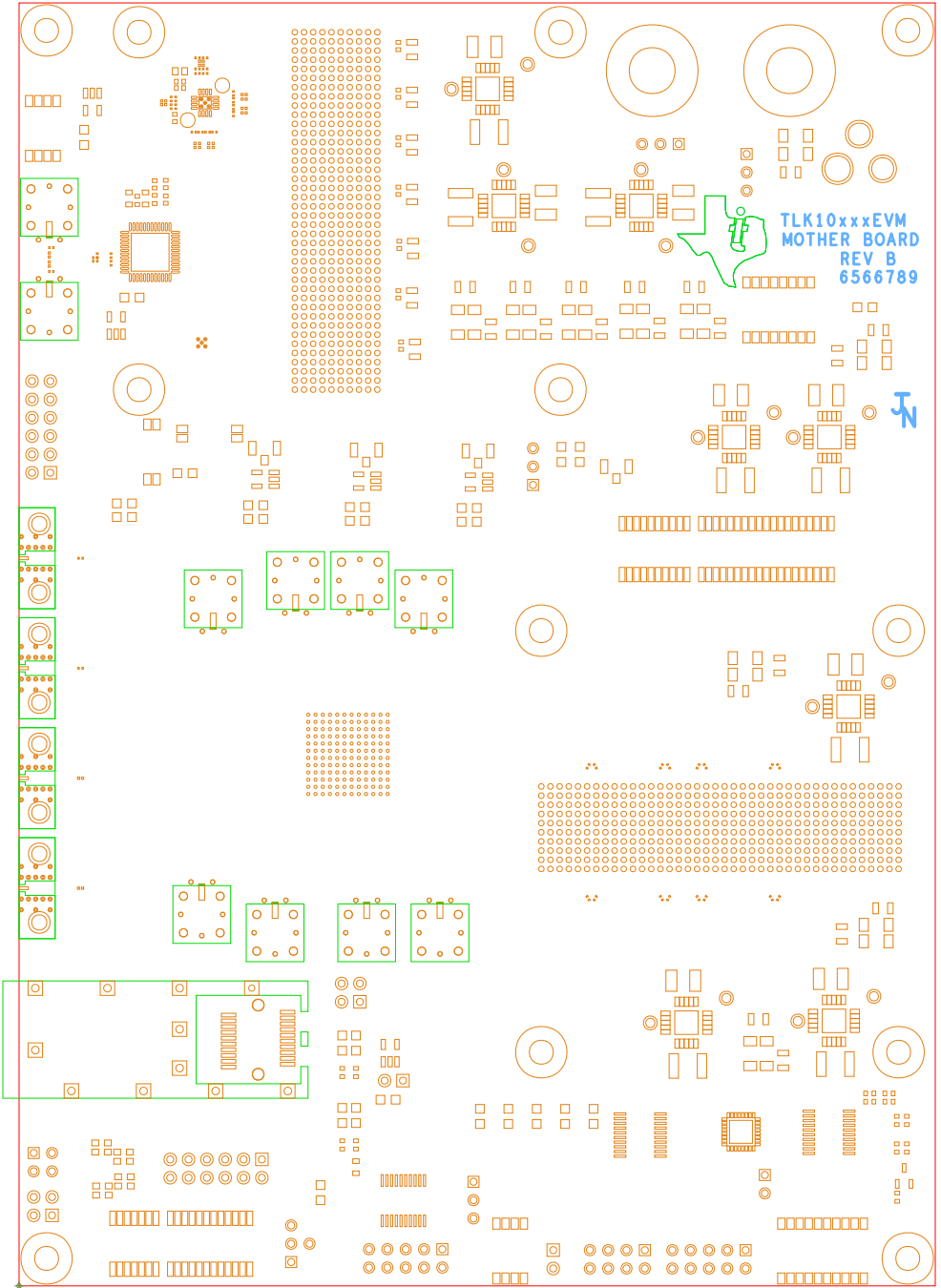
LAYER15-GND



LAYER16-BOTTOM(TESTER)SIDE



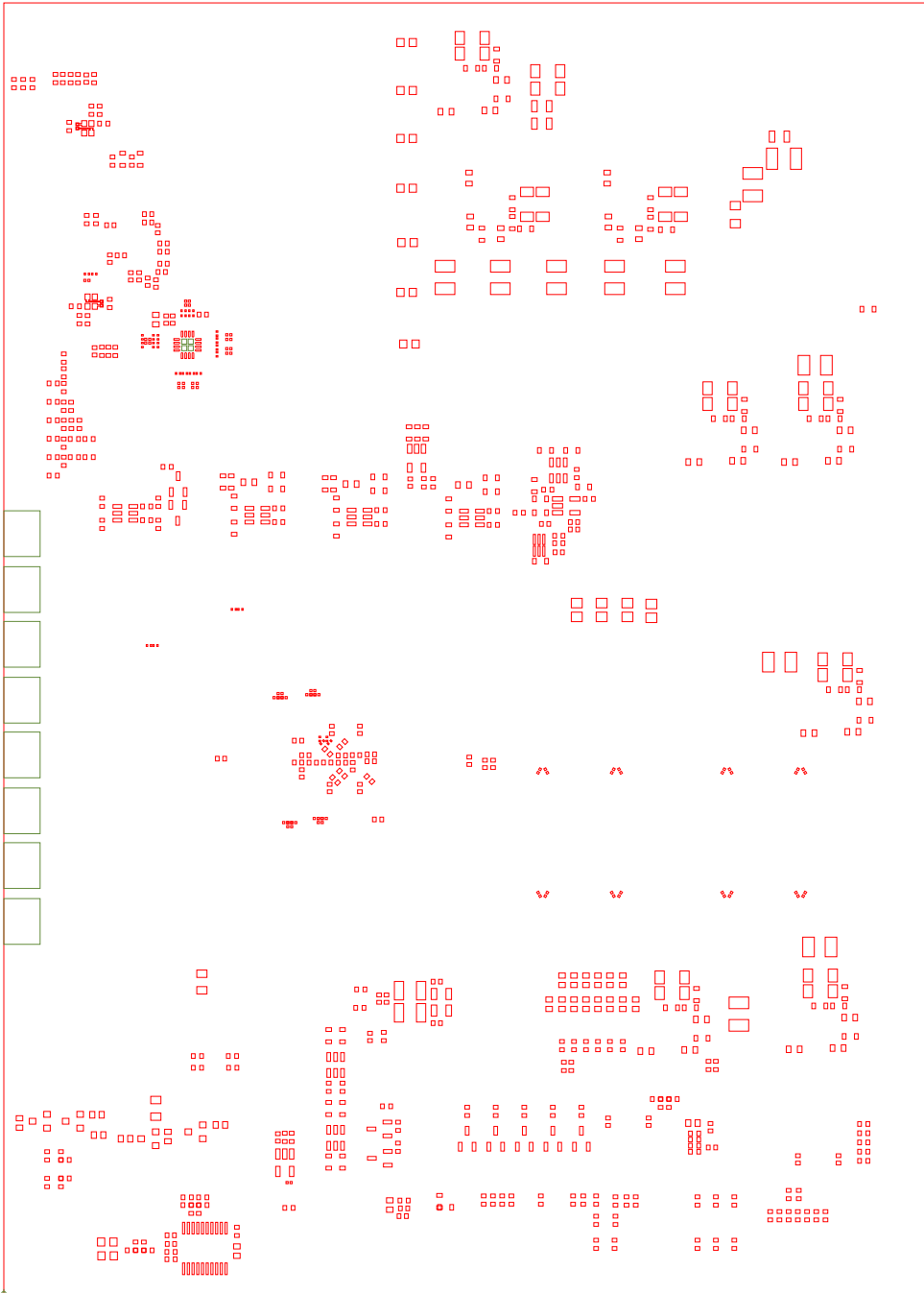
MB



TLK10xxx EVM  
MOTHER BOARD  
REV B  
6566789

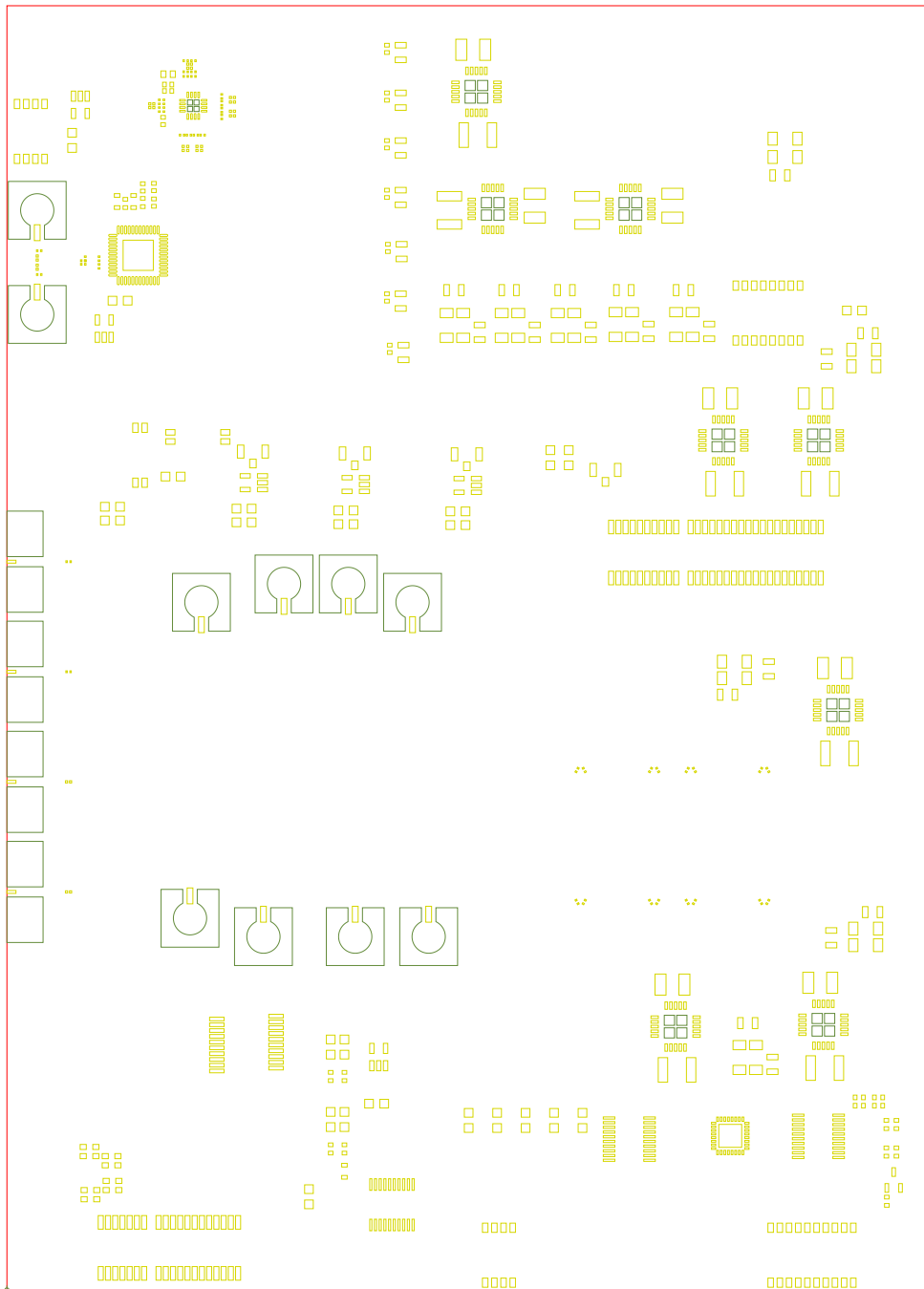
JN

MT

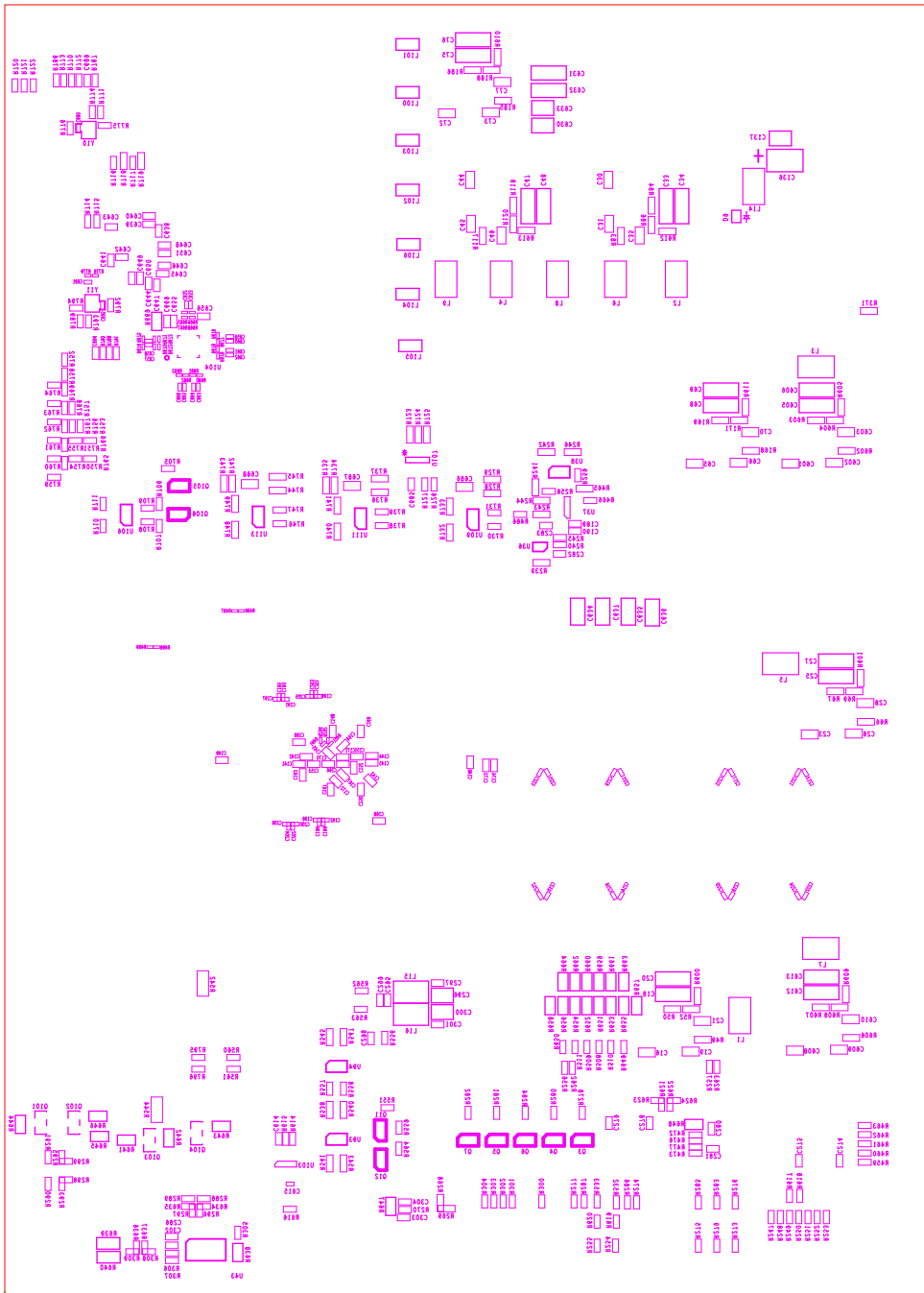


SPB

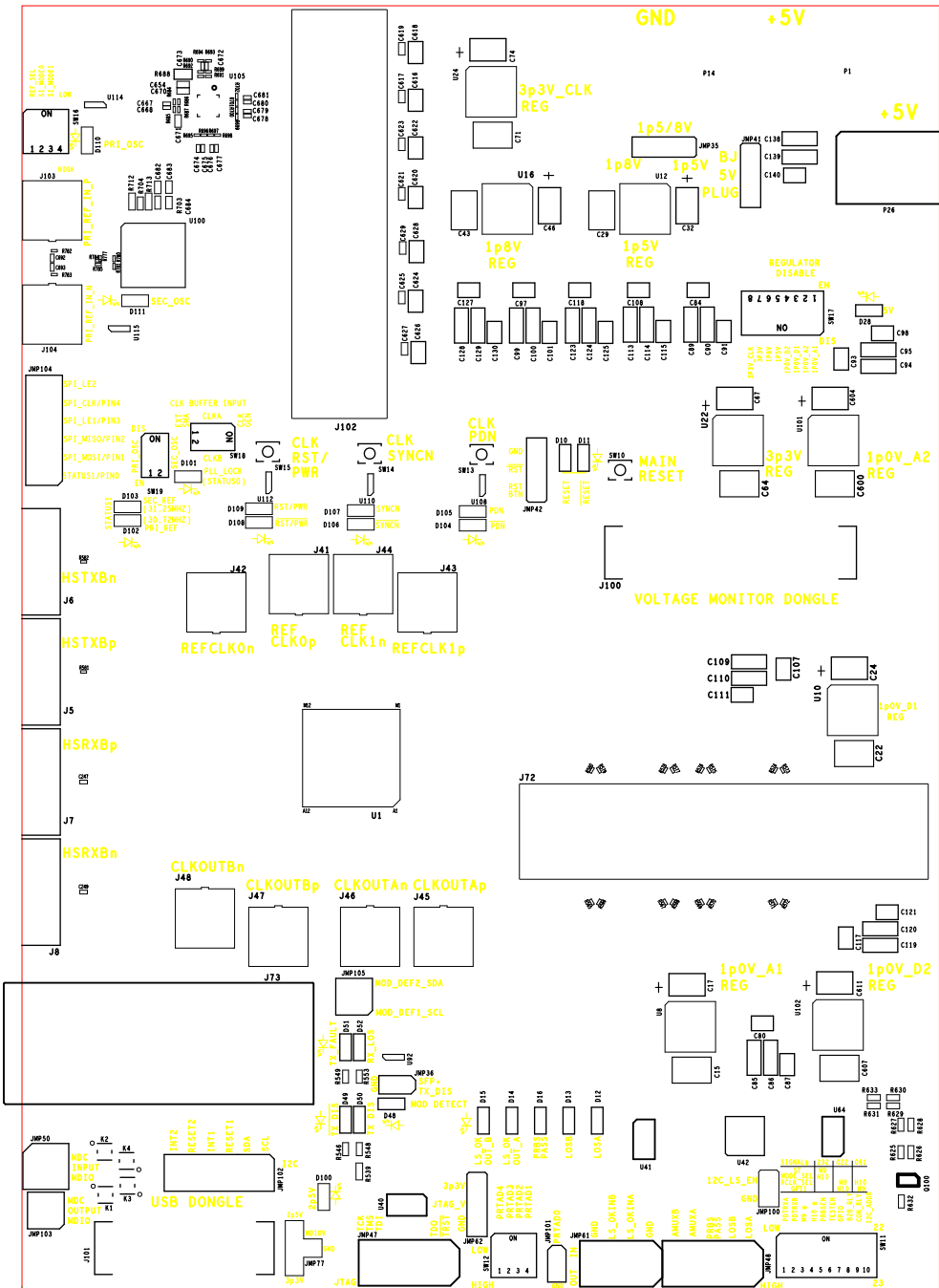




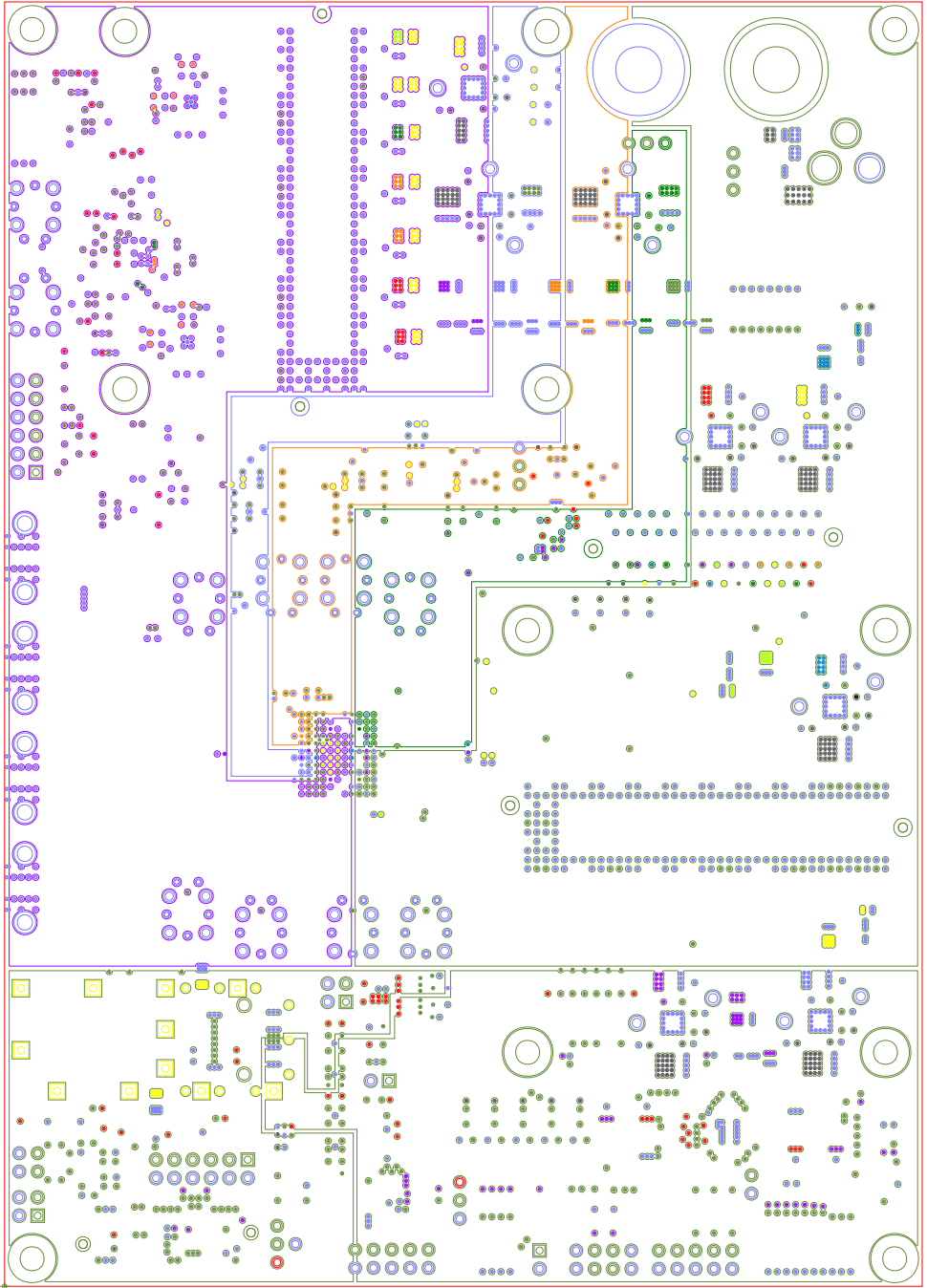
SPT



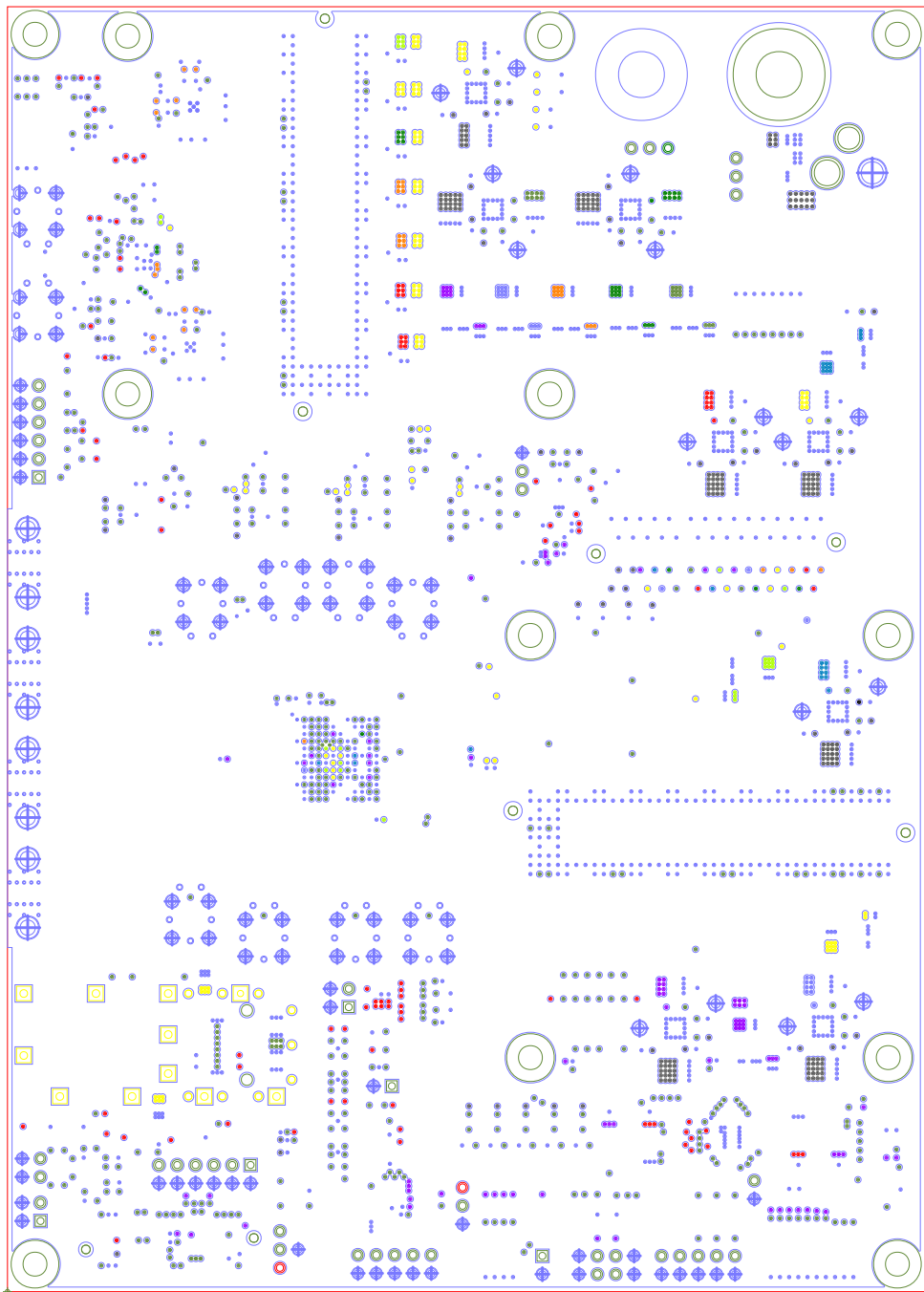
SBW



STW



LAYER 8 - PWR



LAYER7 - GND

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